

March 2014

FQA10N80C_F109 N-Channel QFET® MOSFET

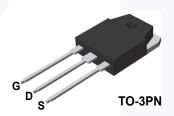
800 V, 10 A, 1.1 Ω

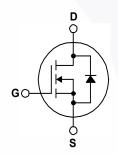
Features

- 10 A, 800 V, $R_{DS(on)}$ = 1.1 Ω (Max.) @ V_{GS} = 10 V, I_D = 5 A
- Low Gate Charge (Typ. 44 nC)
- Low Crss (Typ. 15 pF)
- · 100% Avalanche Tested
- · RoHS compliant

Description

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.





MOSFET Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter			FQA10N80C_F109	Unit
V _{DSS}	Drain to Source Voltage			800	V
I _D	Drain Current	-Continuous (T _C = 25°C)		10	Α
	Drain Current	-Continuous (T _C = 100°C)		6.32	Α
I _{DM}	Drain Current	- Pulsed	(Note 1)	40	Α
V _{GSS}	Gate to Source Voltage			± 30	V
E _{AS}	Single Pulsed Avalanche Energy		(Note 2)	920	mJ
I _{AR}	Avalanche Current		(Note 1)	10	Α
E _{AR}	Repetitive Avalanche Energy		(Note 1)	24	mJ
dv/dt	Peak Diode Recovery dv/dt		(Note 3)	4.0	V/ns
P_{D}	Dawas Dissination	(T _C = 25°C)		240	W
	Power Dissipation	- Derate above 25°C		1.92	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range			-55 to +150	°C
T _L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds			300	°C

Thermal Characteristics

Symbol	Parameter	FQA10N80C_F109	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max	0.52	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max	40	°C/W

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQA10N80C_F109	FQA10N80C	TO-3PN	Tube	N/A	N/A	30 units

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
Off Cha	racteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	800			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		0.98		V/°C
. _	Onto Valta va D. 1 C. 1	V _{DS} = 800 V, V _{GS} = 0 V			10	μΑ
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 640 V, T _C = 125°C			100	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V			-100	nA
On Cha	racteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 5.0 A		0.93	1.1	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 50 V, I _D = 5.0 A		5.8		S
Dynami	c Characteristics					
C _{iss}	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$		2150	2800	pF
C _{oss}	Output Capacitance	f = 1.0 MHz		180	230	pF
C _{rss}	Reverse Transfer Capacitance			15	20	pF
Switchi	ng Characteristics					
t _{d(on)}	Turn-On Delay Time	V _{DD} = 400 V, I _D = 10.0 A,		50	110	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$		130	270	ns
t _{d(off)}	Turn-Off Delay Time	G		90	190	ns
t _f	Turn-Off Fall Time	(Note4)	/	80	170	ns
Q_g	Total Gate Charge	V _{DS} = 640 V, I _D = 10.0 A,		45	58	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V		13.5		nC
Q_{gd}	Gate-Drain Charge	(Note 4)		17		nC
Drain-S	ource Diode Characteristics ar	nd Maximum Ratings				
I _S	Maximum Continuous Drain-Source Dic				10.0	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				40.0	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 10.0 A			1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 10.0 A,		730		ns
Q _{rr}	Reverse Recovery Charge	dI _F / dt = 100 A/μs		10.9		μС

Notes :

^{1.} Repetitive Rating : Pulse width limited by maximum junction temperature.

^{2.} L = 17.3 mH, I $_{AS}$ = 10 A, V $_{DD}$ = 50 V, R $_{G}$ = 25 Ω , starting T $_{J}$ = 25°C.

 $^{3.~}I_{SD} \leq 8.4~A,~di/dt \leq 200~A/\mu s,~V_{DD} \leq BV_{DSS,}~starting~~T_J = 25^{\circ}C.$

^{4.} Essentially independent of operating temperature.

Typical Characteristics

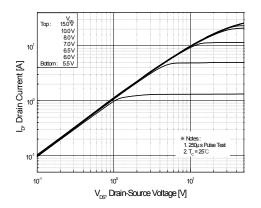


Figure 1. On-Region Characteristics

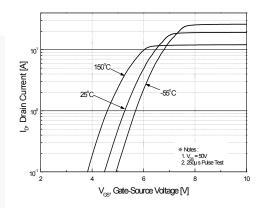


Figure 2. Transfer Characteristics

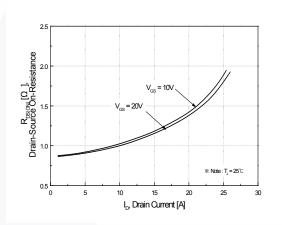


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

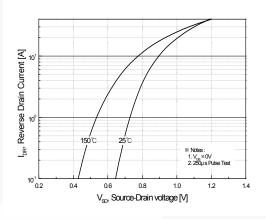


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

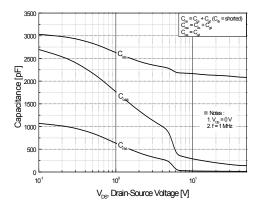


Figure 5. Capacitance Characteristics

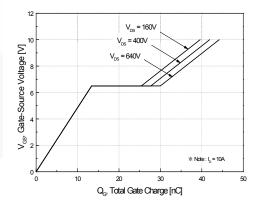


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

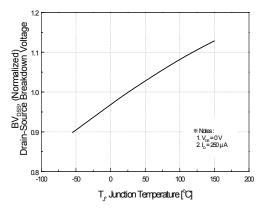


Figure 7. Breakdown Voltage Variation vs Temperature

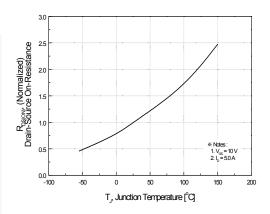


Figure 8. On-Resistance Variation vs Temperature

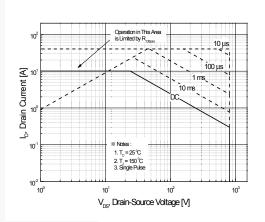


Figure 9. Maximum Safe Operating Area

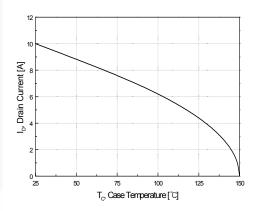


Figure 10. Maximum Drain Current vs Case Temperature

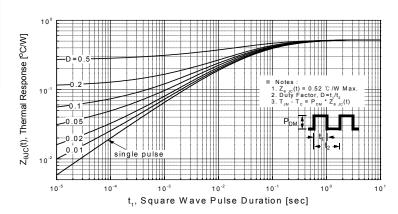


Figure 11. Transient Thermal Response Curve

Figure 12. Gate Charge Test Circuit & Waveform

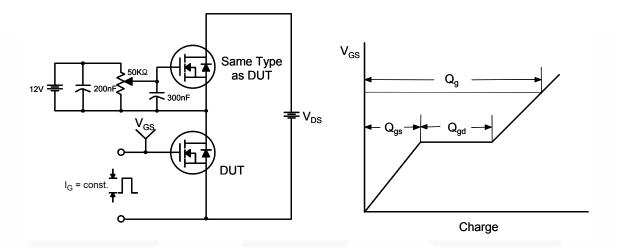


Figure 13. Resistive Switching Test Circuit & Waveforms

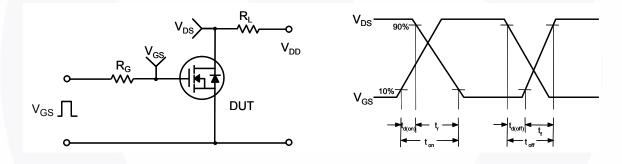
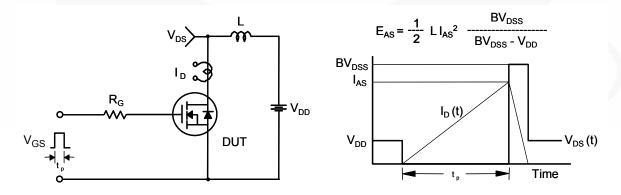


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



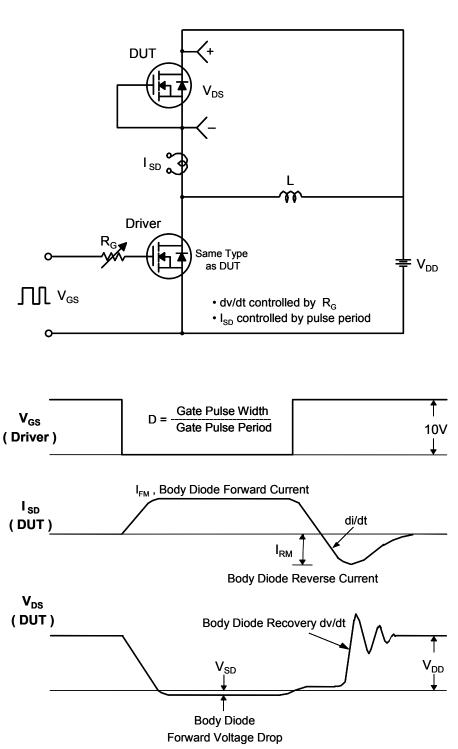
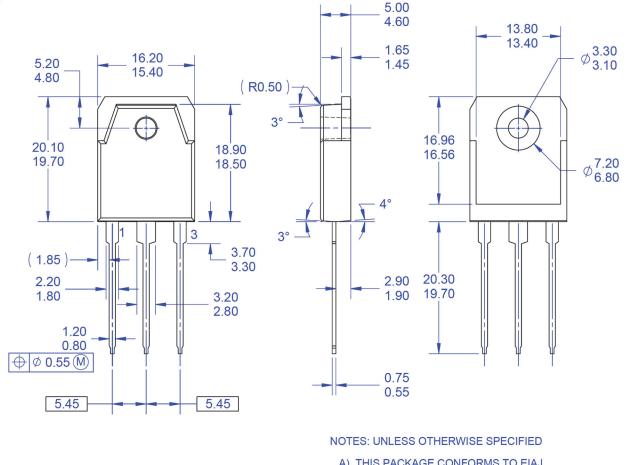
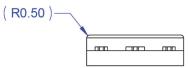


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

Mechanical Dimensions





- A) THIS PACKAGE CONFORMS TO EIAJ SC-65 PACKAGING STANDARD.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- **DIMENSION AND TOLERANCING PER** ASME14.5-2009.
- D) DIMENSIONS ARE EXCLUSSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSSIONS.
 E) DRAWING FILE NAME: TO3PN03AREV1.
- FAIRCHILD SEMICONDUCTOR.

Figure 16. TO3PN, 3-Lead, Plastic, EIAJ SC-65

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